- Designed Specifically for High-Speed Memory Decoders and Data Transmission Systems
- Incorporates Three Enable Inputs to Simplify Cascading and/or Data Reception
- Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

### description

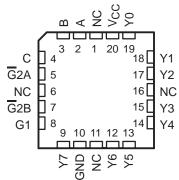
The 'F138 is designed to be used in high-performance memory-decoding or datarouting applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of this decoder and the enable time of the memory are usually less than the typical access time of the memory. This means that the effective system delay introduced by the decoder is negligible.

The conditions at the binary-select inputs and the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can

SN54F1	38.	J PA	CKAGE
SN74F138		D OR N	PACKAGE
(	то	P VIEW)	
, г		$\cup$	
ΑL	1	16	V <sub>CC</sub>   Y0
в [		15	] Y0
с[		14	] Y1
G2A	4	13	] Y2
	5	12	] Y3
G1 [	6	11	] Y4
Y7 [ GND [	7	10	] Y5
gnd [	8	9	] Y6
I			I

SDFS051B - MARCH 1987 - REVISED JULY 1996

SN54F138 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

be implemented without external inverters and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

The SN54F138 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74F138 is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

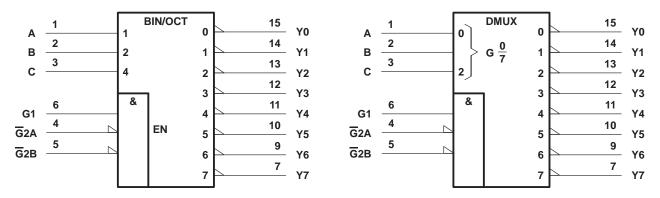


Copyright © 1996, Texas Instruments Incorporated

SDFS051B - MARCH 1987 - REVISED JULY 1996

					F	UNCTIO	N TABL	E					
ENA	BLE INF	PUTS	SEL	ECT INP	UTS				OUT	PUTS			
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Н	Х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
Х	Х	Н	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	н
L	Х	Х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	н
н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	н
н	L	L	L	L	Н	н	L	Н	Н	Н	Н	Н	н
н	L	L	L	Н	L	н	Н	L	Н	Н	Н	Н	н
н	L	L	L	Н	Н	н	Н	Н	L	Н	Н	Н	н
н	L	L	Н	L	L	н	Н	Н	Н	L	Н	Н	н
н	L	L	Н	L	Н	н	Н	Н	Н	Н	L	Н	Н
н	L	L	Н	Н	L	н	Н	Н	Н	Н	Н	L	Н
н	L	L	Н	Н	Н	н	Н	Н	Н	Н	Н	Н	L

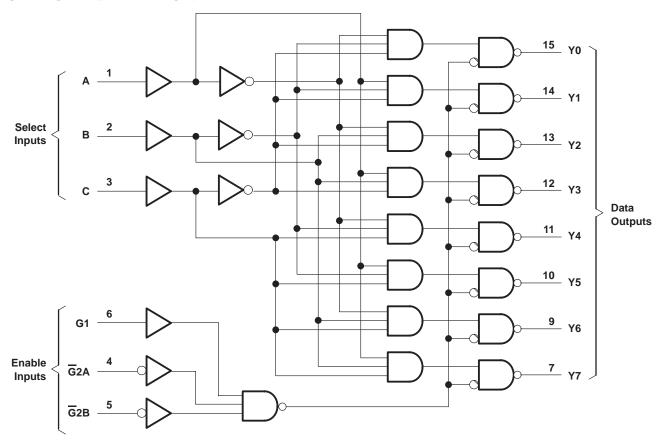
logic symbols (alternatives)<sup>†</sup>



<sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



SDFS051B - MARCH 1987 - REVISED JULY 1996



logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

SDFS051B – MARCH 1987 – REVISED JULY 1996

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (see Note 1)	
Input current range	
Voltage range applied to any output in the high state	$\dots -0.5$ V to V <sub>CC</sub>
Current into any output in the low state	40 mA
Operating free-air temperature range: SN54F138	
SN74F138	0°C to 70°C
Storage temperature range	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

#### recommended operating conditions

		S	N54F138	3	S	N74F138	3	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
IIК	Input clamp current			-18			-18	mA
ЮН	High-level output current			- 1			- 1	mA
I <sub>OL</sub>	Low-level output current			20			20	mA
т <sub>А</sub>	Operating free-air temperature	-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	те	ST CONDITIONS	s	N54F13	3	S	N74F138	3	UNIT
PARAMETER		ST CONDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	lj = -18 mA			-1.2			-1.2	V
Voн	$V_{CC} = 4.5 V,$	I <sub>OH</sub> = - 1 mA	2.5	3.4		2.5	3.4		V
VOH	V <sub>CC</sub> = 4.75 V,	I <sub>OH</sub> = - 1 mA				2.7			v
VOL	$V_{CC} = 4.5 V,$	I <sub>OL</sub> = 20 mA		0.3	0.5		0.3	0.5	V
lı	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 7 V			0.1			0.1	mA
Чн	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V			20			20	μΑ
Ι <sub>ΙL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			- 0.6			- 0.6	mA
los§	V <sub>CC</sub> = 5.5 V,	$V_{O} = 0$	-60		-150	-60		-150	mA
Icc	V <sub>CC</sub> = 5.5 V,	See Note 2		13	20		13	20	mA

<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V,  $T_A = 25^{\circ}$ C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: ICC is measured with outputs enabled and open.



SDFS051B - MARCH 1987 - REVISED JULY 1996

### switching characteristics (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL RL	c = 5 V, = 50 PF = 500 Ω = 25°C	,	CL RL	<b>= 50 PF</b> , <b>= 500</b> Ω			UNIT
	, , ,	(001101)	′F138			SN54	F138	SN74	F138	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A, B, or C	Y	2.7	5.2	7.5	2.7	12	2.7	8.5	ns
<sup>t</sup> PHL	A, B, 01 C	ř	3.2	5.7	8	3.2	9.5	3.2	9	115
tPLH	$\overline{G}2A$ or $\overline{G}2B$	Y	2.7	5	7	2.7	11	2.7	8	ns
<sup>t</sup> PHL	GZA OF GZB	ř	2.2	4.9	7	2.2	8	2.2	7.5	115
<sup>t</sup> PLH	G1	Y	3.2	5.8	8	3.2	12.5	3.2	9	
<sup>t</sup> PHL	61		2.7	5.2	7.5	2.7	8.5	2.7	8.5	ns

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 3: Load circuits and waveforms are shown in Section 1.





6-Feb-2020

### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
5000 0750004004	(1)	1000			-	(2)		(3)	55 1 405	(4/5)	
5962-9758201Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9758201Q2A SNJ54F 138FK	Samples
5962-9758201QEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9758201QE A SNJ54F138J	Samples
5962-9758201QFA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9758201QF A SNJ54F138W	Samples
JM38510/33701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 33701B2A	Samples
JM38510/33701BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 33701BEA	Samples
JM38510/33701BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 33701BFA	Samples
M38510/33701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 33701B2A	Samples
M38510/33701BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 33701BEA	Samples
M38510/33701BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 33701BFA	Samples
SN54F138J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54F138J	Samples
SN74F138D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	F138	Samples
SN74F138DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	F138	Samples
SN74F138DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	F138	Samples
SN74F138N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74F138N	Samples
SN74F138NE4	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74F138N	Samples



6-Feb-2020

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74F138NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F138	Samples
SNJ54F138FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9758201Q2A SNJ54F 138FK	Samples
SNJ54F138J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9758201QE A SNJ54F138J	Samples
SNJ54F138W	ACTIVE	CFP	W	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9758201QF A SNJ54F138W	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



www.ti.com

6-Feb-2020

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54F138, SN74F138 :

- Catalog: SN74F138
- Military: SN54F138

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

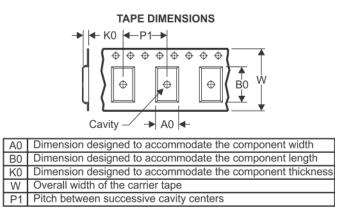
# PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal			
	_	_	

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F138DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TEXAS INSTRUMENTS

www.ti.com

# PACKAGE MATERIALS INFORMATION

8-Apr-2013



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F138DR	SOIC	D	16	2500	333.2	345.9	28.6

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

# D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### MECHANICAL DATA

### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

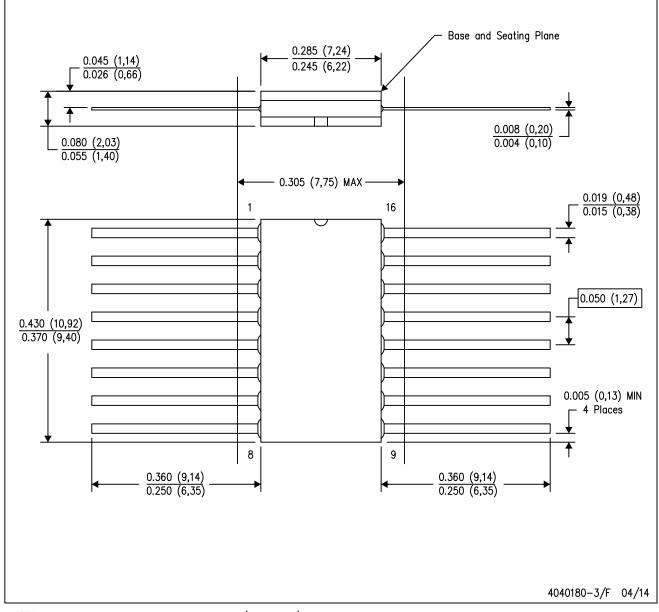
**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP2-F16



J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



#### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2020, Texas Instruments Incorporated